

DECLARATION

I, Seiichi Kuwai, residing at 7-17-5, Okusawa, Setagaya-ku, Tokyo, Japan hereby certify that I am the translator of the attached document, namely, the certified copy of Japanese Patent Application No. Heisei 10-138365, and I certify that the following is true translation thereof to the best of my knowledge and belief.

Date: November 20, 2003


Seiichi KUWAI

PATENT OFFICE JAPANESE GOVERNMENT

This is to certify that the annexed is a true copy of the
following application as filed with this office.

Date of Application : May 20, 1998

Application Number : Heisei 10-138365

Applicant(s): NEC Corporation

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Commissioner, Patent Office

TAKESHI ISAYAMA

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[Title of Invention] Method for Cleaning Wafers

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[Document] Specification 1 copy

[Document] Drawings 1 copy

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